SEMICONDUCTOR PACKAGE AND METHOD FOR MANUFACTURING THE SAME

Appl. No.

10/710,399

Confirmation No.

4398

Applicant

Min-Jer Lin

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TC/A.U.

2818

Examiner

: DAO H. NGUYEN

Docket No.

: LKSP0027USA0

Customer No.

27765

Commissioner for Patents

P.O. Box 1450

Alexandria VA 22313-1450

AMENDMENT

5 Sir:

In response to the Office action of June 9, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks/Arguments begin on page 7 of this paper.